

MT8275N5

N-Channel Enhancement Mode Field Effect Transistor

Product Summary

- $V_{DS} = 20V$
- $I_D = 180A$
- $R_{DS(ON)} = 1.4m\Omega @V_{GS} = 4.5V$
- $R_{DS(ON)} = 1.6m\Omega @V_{GS} = 2.5V$

Features

- Advanced Trench Process Technology.
- High Density Cell Design for Ultra Low On-Resistance.
- Lead free product is acquired.
- RoHS Compliant.
- PDFN5x6-8L Package

Applications

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

Absolute Maximum Ratings ($T_A = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Steady State	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 12	V
I_D	Continuous Drain Current ¹	180	A
I_{DM}	Pulsed Drain Current ²		
I_S	Continuous Source Current (Diode Conduction) ¹	180	A
E_{AS}	Single Pulse Drain-Source Avalanche Energy ³	1510	mJ
P_D	Maximum Power Dissipation	110	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55~150	$^\circ C$

Notes:

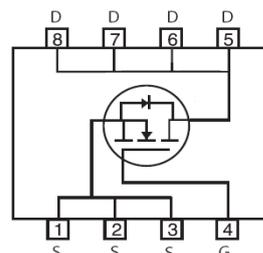
1. Surface Mounted on 1" x 1" FR4 Board, $t \leq 10$ Sec.
2. Pulse width limited by maximum junction temperature.
3. The test condition is $T_J = 25^\circ C$, $V_{DD} = 30V$, $V_{GS} = 10V$, $L = 0.1mH$, $R_G = 25\Omega$, $I_{AS} = 50A$.



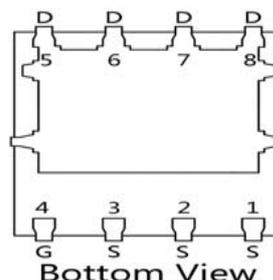
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Simplified Schematic



MARKING DIAGRAM & PIN ASSIGNMENT



Thermal Characteristic

Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.15	$^{\circ}C/W$
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Electrical Characteristics ($T_C=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	20	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=20V, V_{GS}=0V$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	± 100	nA
On Characteristics						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5	0.75	1.2	V
Drain-Source On-State Resistance ^a	$R_{DS(ON)}$	$V_{GS}=4.5V, I_D=20A$	-	1.4	2.0	m Ω
		$V_{GS}=2.5V, I_D=15A$		1.6	2.4	
Forward Transconductance	g_{FS}	$V_{DS}=5V, I_D=20A$	100	-	-	S
Dynamic Characteristics^b						
Input Capacitance	C_{iss}	$V_{DS}=10V, V_{GS}=0V,$ $F=1.0MHz$	-	5000	-	PF
Output Capacitance	C_{oss}		-	1200	-	PF
Reverse Transfer Capacitance	C_{rss}		-	900	-	PF
Switching Characteristics						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=10V, I_D=2A, R_L=15\Omega$ $V_{GS}=10V, R_G=2.5\Omega$	-	12	-	nS
Turn-on Rise Time	t_r		-	13	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	45	-	nS
Turn-Off Fall Time	t_f		-	32	-	nS
Total Gate Charge	Q_g	$V_{DS}=10V, I_D=20A,$ $V_{GS}=10V$	-	70		nC
Gate-Source Charge	Q_{gs}		-	16		nC
Gate-Drain Charge	Q_{gd}		-	20		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=20A$	-		1.2	V
Diode Forward Current	I_S		-	-	150	A
Reverse Recovery Time	t_{rr}	$T_J = 25^{\circ}C, I_F = 20A$ $di/dt = 100A/\mu s$	-	49	-	nS
Reverse Recovery Charge	Q_{rr}		-	66	-	nC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Note:

- a. Pulse test; pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
b. Guaranteed by design, not subject to production testing.

Typical Electrical and Thermal Characteristics (Curves)

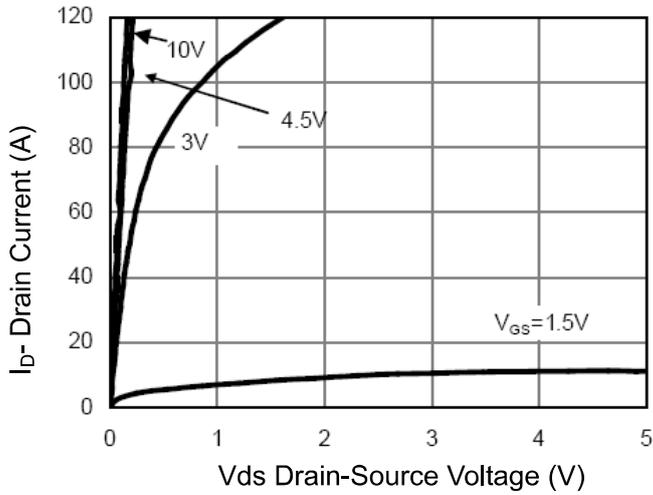


Figure 1 Output Characteristics

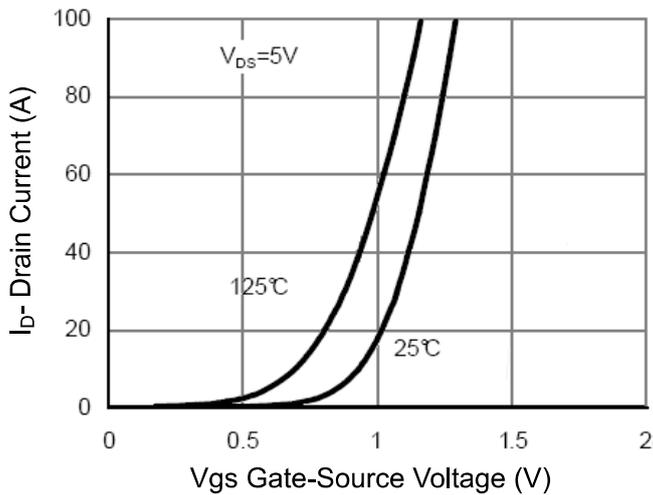


Figure 2 Transfer Characteristics

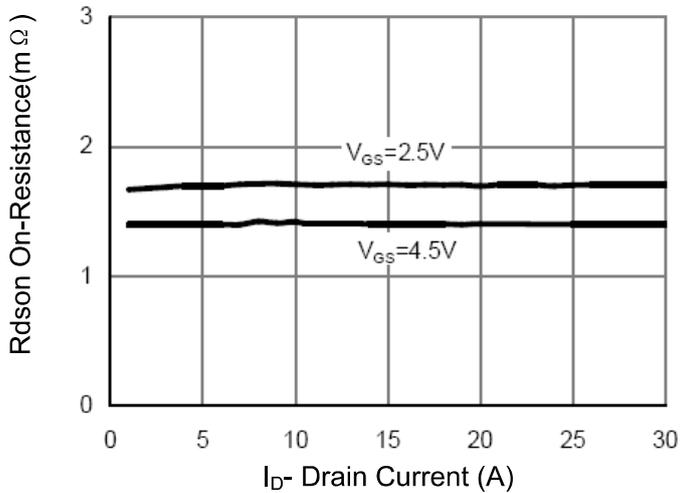


Figure 3 Rdson- Drain Current

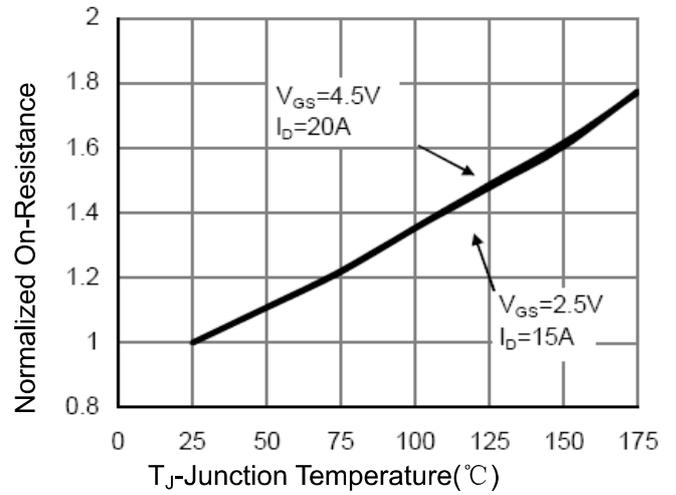


Figure 4 Rdson-Junction Temperature

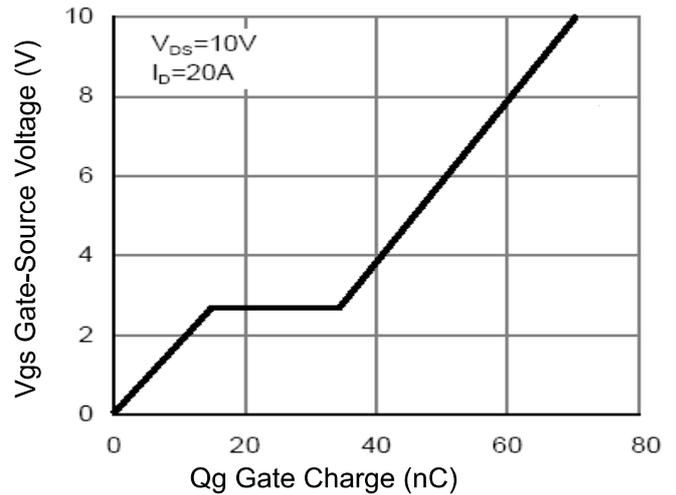


Figure 5 Gate Charge

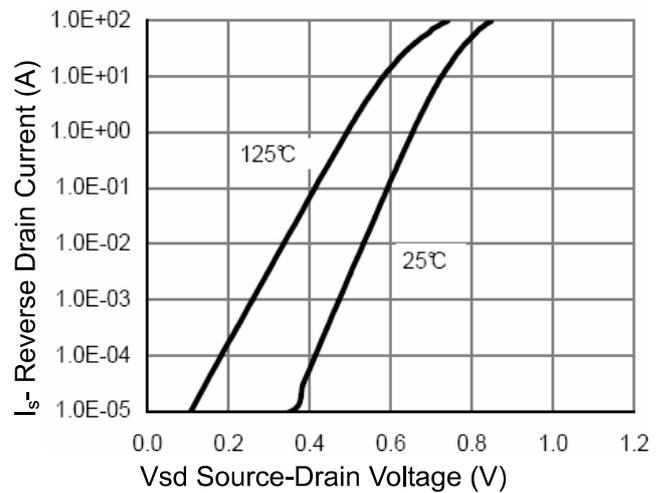


Figure 6 Source- Drain Diode Forward

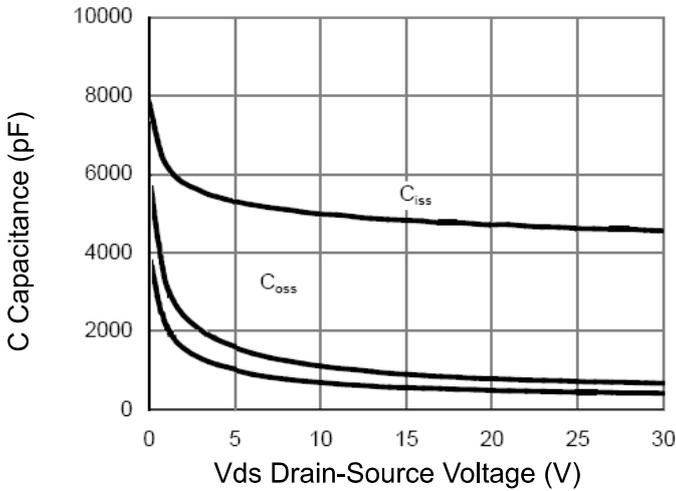


Figure 7 Capacitance vs Vds

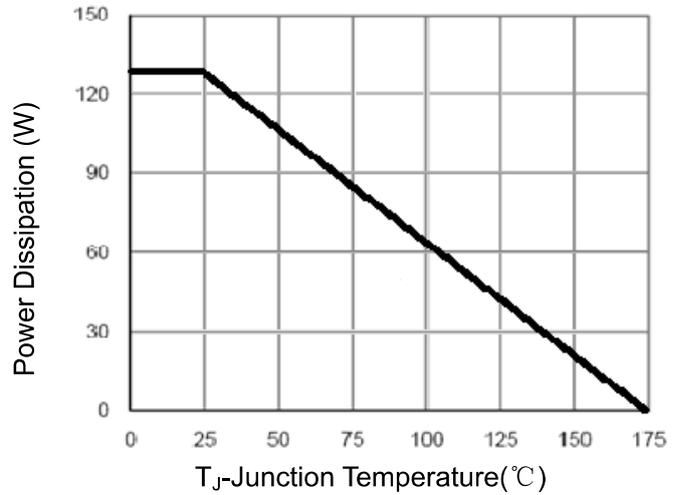


Figure 9 Power De-rating

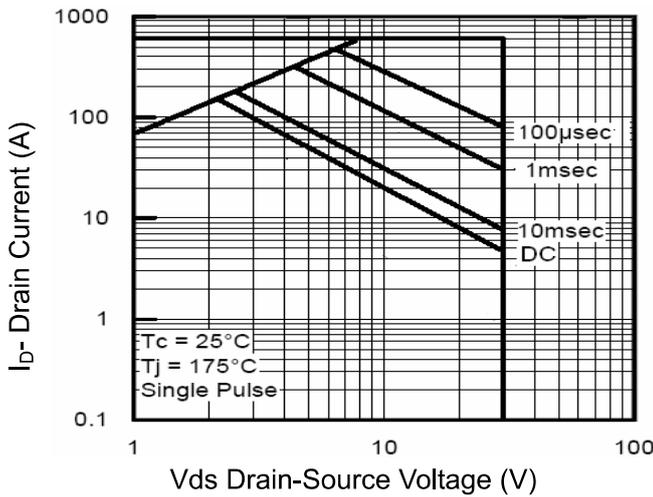


Figure 8 Safe Operation Area

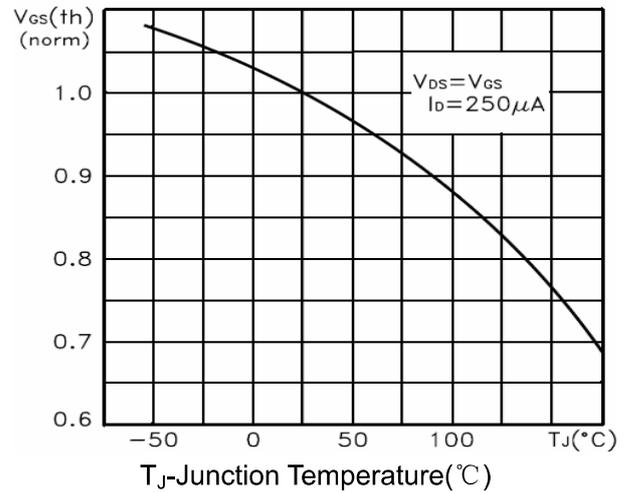


Figure 10 VGS(th) vs Junction Temperature

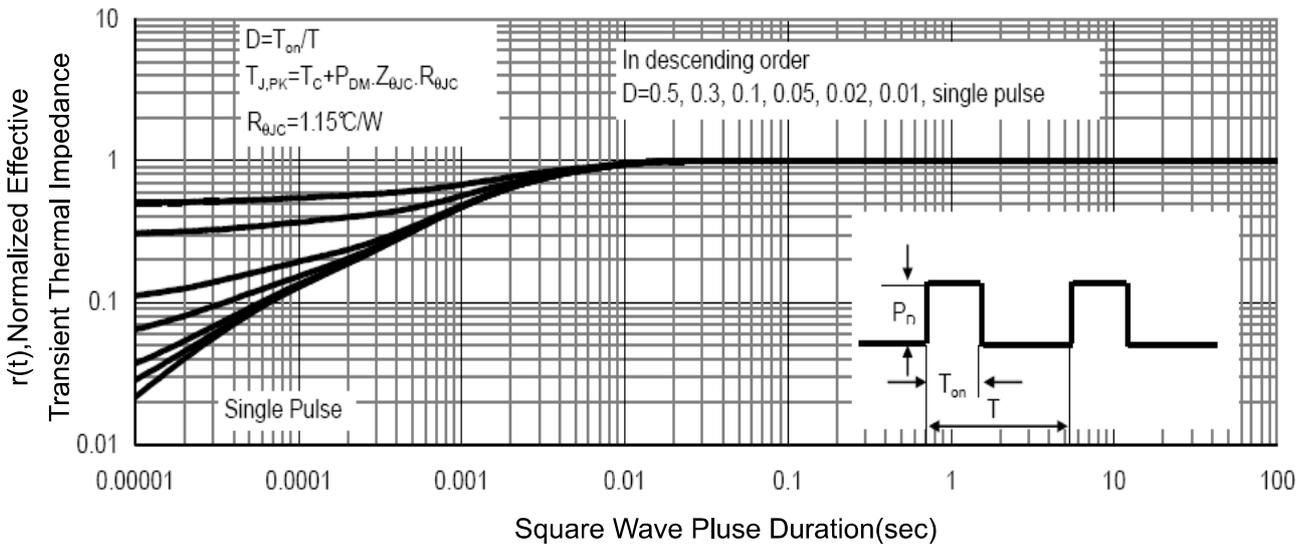
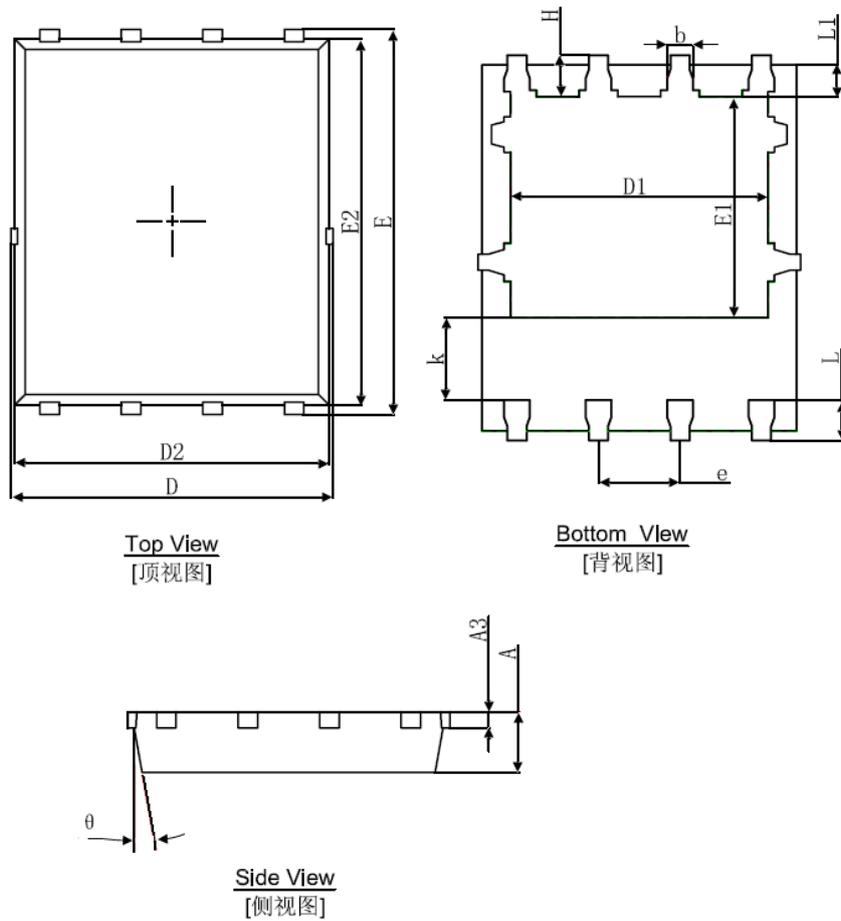


Figure 11 Normalized Maximum Transient Thermal Impedance

PDFN5X6-8L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
K	1.190	1.390	0.047	0.055
b	0.035	0.450	0.014	0.018
e	1.270(TYP.)		0.050(TYP.)	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	8°	12°	8°	12°

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